### INTEGRATED CIRCUITS

## DATA SHEET

# NE/SE5539 High frequency operational amplifier

Product data
Supersedes data of 2001 Aug 03
File under Integrated Circuits, IC11 Data Handbook





## High frequency operational amplifier

**NE/SE5539** 

#### **DESCRIPTION**

The NE/SE5539 is a very wide bandwidth, high slew rate, monolithic operational amplifier for use in video amplifiers, RF amplifiers, and extremely high slew rate amplifiers.

Emitter-follower inputs provide a true differential input impedance device. Proper external compensation will allow design operation over a wide range of closed-loop gains, both inverting and non-inverting, to meet specific design requirements.

#### **FEATURES**

Bandwidth

- Unity gain: 350 MHz - Full power: 48 MHz - GBW: 1.2 GHz at 17 dB

Slew rate: 600/Vµs A<sub>VOL</sub>: 52 dB typical

Low noise: 4 nV√Hz typical

#### **PIN CONFIGURATION**

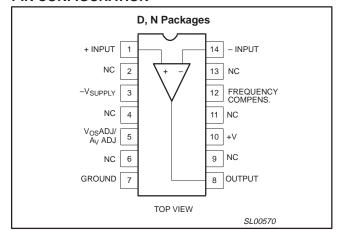


Figure 1. Pin Configuration

#### **APPLICATIONS**

- High speed datacom
- Video monitors & TV
- Satellite communications
- Image processing
- RF instrumentation & oscillators
- Magnetic storage

#### ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
14-Pin Plastic Dual In-Line Package (DIP)	0 °C to +70 °C	NE5539N	SOT27-1
14-Pin Plastic Small Outline (SO) package	0 °C to +70 °C	NE5539D	SOT108-1
14-Pin Plastic Dual In-Line Package (DIP)	−55 °C to +125 °C	SE5539N	SOT27-1

#### ABSOLUTE MAXIMUM RATINGS1

SYMBOL	PARAMETER	RATING	UNITS
V <sub>CC</sub>	Supply voltage	±12	V
P <sub>D(max)</sub>	Maximum power dissipation; T <sub>amb</sub> = 25 °C (still-air) <sup>2</sup> N package D package	1.45 0.99	W W
T <sub>amb</sub>	Operating temperature range NE5539D, NE5539N SE5539N	0 to +70 -55 to +125	°C °C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C
Tj	Max junction temperature	+150	°C
T <sub>sld</sub>	Lead soldering temperature (10 sec max)	+230	°C

#### NOTES:

- 1. Differential input voltage should not exceed 0.25 V to prevent excessive input bias current and common-mode voltage 2.5 V. These voltage limits may be exceeded if current is limited to less than 10 mA.
- 2. Derate above 25 °C, at the following rates: N package at 11.6 mW/°C

  - D package at 7.9 mW/°C

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#### **EQUIVALENT CIRCUIT**

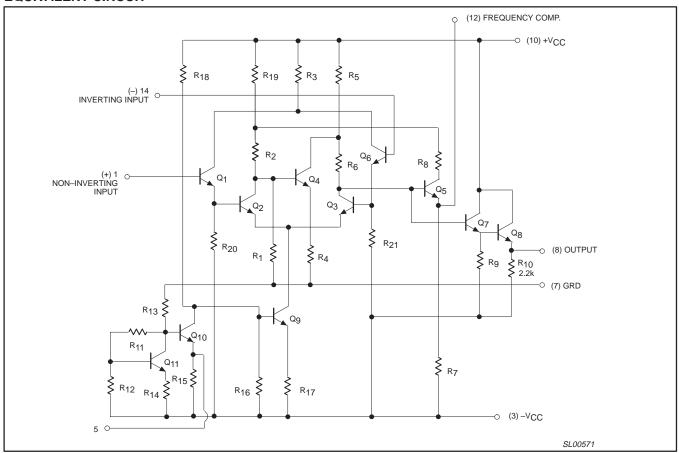


Figure 2. Equivalent Circuit

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#### DC ELECTRICAL CHARACTERISTICS

 $V_{CC}$  =  $\pm 8$  V,  $T_{amb}$  = 25  $^{\circ}C;$  unless otherwise specified.

					SE5539			NE5539			
SYMBOL	PARAMETER	TEST CONDIT	TIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS	
		V <sub>O</sub> = 0 V;	Over temp.		2	5					
V <sub>OS</sub>	Input offset voltage	$R_S = 100 \Omega$	T <sub>amb</sub> = 25 °C		2	3		2.5	5	m∨	
ΔV <sub>OS</sub> /ΔT					5			5		μV/°C	
	lanut effect coment		Over temp.		0.1	3					
los	Input offset current		T <sub>amb</sub> = 25 °C		0.1	1			2	μΑ	
$\Delta I_{OS}/\Delta T$					0.5			0.5		nA/°C	
	Input bias current		Over temp.		6	25					
I <sub>B</sub>	input bias current		T <sub>amb</sub> = 25 °C		5	13		5	20	μΑ	
$\Delta I_B/\Delta T$					10			10		nA/°C	
CMRR	Common mode rejection ratio	$F = 1 \text{ kHz}; R_S = 100 \Omega$	2; V <sub>CM</sub> ±1.7 V	70	80		70	80		dB	
CIVIKK	Common mode rejection ratio		Over temp.	70	80					uБ	
R <sub>IN</sub>	Input impedance				100			100		kΩ	
R <sub>OUT</sub>	Output impedance				10			10		Ω	
		$R_L = 150 \Omega$ to GND	+Swing				+2.3	+2.7		V	
		and 470 $\Omega$ to $-V_{CC}$	-Swing				-1.7	-2.2		l	
V	Output valtage eving	$R_L = 25 \Omega$ to GND	+Swing	+2.3	+3.0					V	
V <sub>OUT</sub>	Output voltage swing	Over temp.	-Swing	-1.5	-2.1					ľ	
		$R_L = 25 \Omega$ to GND	+Swing	+2.5	+3.1					V	
		T <sub>amb</sub> = 25 °C	-Swing	-2.0	-2.7					l	
	Positivo aupply aurrent	$V_0 = 0 \text{ V, } R_1 = \infty; 0$	Over temp.		14	18				mA	
I <sub>CC+</sub>	Positive supply current	$V_0 = 0 \text{ V}, R_1 = \infty; T_0$	<sub>amb</sub> = 25 °C		14	17		14	18	IIIA	
	Negative eventy everent	$V_0 = 0 \text{ V, R}_1 = \infty$ ;	Over temp.		11	15					
I <sub>CC</sub> _	Negative supply current	$V_0 = 0 \text{ V}, R_1 = \infty; T_2$	<sub>amb</sub> = 25 °C		11	14		11	15	mA	
PSRR	Dower oupply rejection ratio	$\Delta V_{CC} = \pm 1 \text{ V; Ov}$	er temp.		300	1000					
FORK	Power supply rejection ratio	$\Delta V_{CC} = \pm 1 \text{ V; T}_{am}$	<sub>ib</sub> = 25 °C					200	1000	μV/V	
		$V_{O} = +2.3 \text{ V}, -$ R <sub>L</sub> = 150 $\Omega$ to GND, 4	1.7 V; 70 Ω to –V <sub>CC</sub>				47	52	57	dB	
		$V_0 = +2.3 \text{ V}, -1.7 \text{ V};$	Over temp.							40	
$A_{VOL}$	Large signal voltage gain	$R_L = 2 \Omega$ to GND	T <sub>amb</sub> = 25 °C				47	52	57	dB	
		$V_O = +2.5 \text{ V}, -2.0 \text{ V};$ $R_L = 2 \Omega \text{ to GND}$	Over temp.	46		60				dB	
		$R_L = 2 \Omega$ to GND	T <sub>amb</sub> = 25 °C	48	53	58				UD.	

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#### DC ELECTRICAL CHARACTERISTICS

 $V_{CC}$  = ±6 V,  $T_{amb}$  = 25  $^{\circ}C;$  unless otherwise specified.

CVMDOL	DADAMETER	TEC	CONDITIONS			SE5539		LINUTC
SYMBOL	PARAMETER	IE9	TEST CONDITIONS					UNITS
V	Input offset voltage			Over temp.		2	5	mV
Vos	Input onset voltage			T <sub>amb</sub> = 25 °C		2	3	IIIV
laa	Input offset current			Over temp.		0.1	3	μА
los	input onset current			T <sub>amb</sub> = 25 °C		0.1	1	μΑ
1_	Input bias current			Over temp.		5	20	μА
I <sub>B</sub>	Input bias current			T <sub>amb</sub> = 25 °C		4	10	μΑ
CMRR	Common-mode rejection ratio	V <sub>CM</sub> = ±	1.3 V; R <sub>S</sub> = 100	Ω	70	85		dB
loo	Positive supply current			Over temp.		11	14	mA
Icc+	Positive supply current		T <sub>amb</sub> = 25 °C		11	13	IIIA	
laa	Negative supply current			Over temp.		8	11	mA
Icc-	Negative supply current			$T_{amb} = 25^{\circ} C$		8	10	IIIA
PSRR	Power supply rejection ratio	$\Delta V_{CC} = \pm$	1 \/	Over temp.		300	1000	μV/V
FORK	Power supply rejection ratio	$\nabla ACC = T$		T <sub>amb</sub> = 25 °C				μν/ν
			Over temp.	+Swing	+1.4	+2.0		
\/	Output voltage swing	$R_L = 150 \Omega$ to GND	Over temp.	-Swing	-1.1	-1.7		V
V <sub>OUT</sub>	Output voltage swiftg	and 390 $\Omega$ to $-V_{CC}$	T 25 °C	+Swing	+1.5	+2.0		]
			T <sub>amb</sub> = 25 °C	-Swing	-1.4	-1.8		

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#### **AC ELECTRICAL CHARACTERISTICS**

 $V_{CC}$  =  $\pm 8$  V,  $R_L$  = 150  $\Omega$  to GND and 470  $\Omega$  to  $-V_{CC}$ , unless otherwise specified.

CVMDOL	DADAMETED	TEST CONDITIONS		SE5539			NE5539		UNITS
SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIIS
BW	Gain bandwidth product	$A_{CL} = 7, V_O = 0.1 V_{P-P}$		1200			1200		MHz
	Small signal bandwidth	$A_{CL} = 2$ , $R_L = 150 \Omega^1$		110			110		MHz
t <sub>S</sub>	Settling time	$A_{CL} = 2$ , $R_L = 150 \Omega^1$		15			15		ns
SR	Slew rate	$A_{CL} = 2$ , $R_L = 150 \Omega^1$		600			600		V/μs
t <sub>PD</sub>	Propagation delay	$A_{CL} = 2$ , $R_L = 150 \Omega^1$		7			7		ns
	Full power response	$A_{CL} = 2$ , $R_L = 150 \Omega^1$		48			48		MHz
	Full power response	$A_V = 7$ , $R_L = 150 \Omega^1$		20			20		MHz
	Input noise voltage	$R_S = 50 \Omega$ , 1 MHz		4			4		nV/√Hz
	Input noise current	1 MHz		6			6		pA/√Hz

#### NOTE:

#### **AC ELECTRICAL CHARACTERISTICS**

 $V_{CC}$  =  $\pm 6$  V,  $R_L$  = 150  $\Omega$  to GND and 390  $\Omega$  to  $-V_{CC}$ , unless otherwise specified.

SYMBOL	PARAMETER	TEST CONDITIONS		SE5539		UNITS
STIMBUL	PARAWETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
BW	Gain bandwidth product	A <sub>CL</sub> = 7		700		MHz
DVV	Small signal bandwidth	$A_{CL} = 2^1$		120		IVITZ
t <sub>S</sub>	Settling time	$A_{CL} = 2^{1}$		23		ns
SR	Slew rate	$A_{CL} = 2^{1}$		330		V/μs
t <sub>PD</sub>	Propagation delay	$A_{CL} = 2^{1}$		4.5		ns
	Full power response	$A_{CL} = 2^{1}$		20		MHz

6

#### NOTE:

#### **TYPICAL PERFORMANCE CURVES**

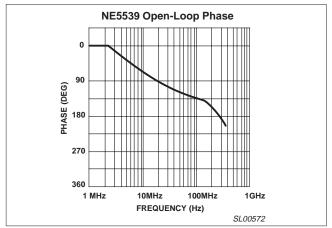


Figure 3. NE5539 Open-Loop Phase

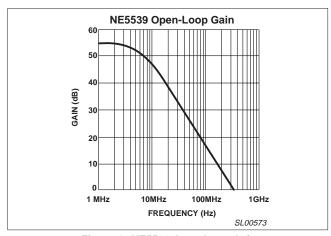


Figure 4. NE5539 Open-Loop Gain

<sup>1.</sup> External compensation.

<sup>1.</sup> External compensation.

#### TYPICAL PERFORMANCE CURVES (Continued)

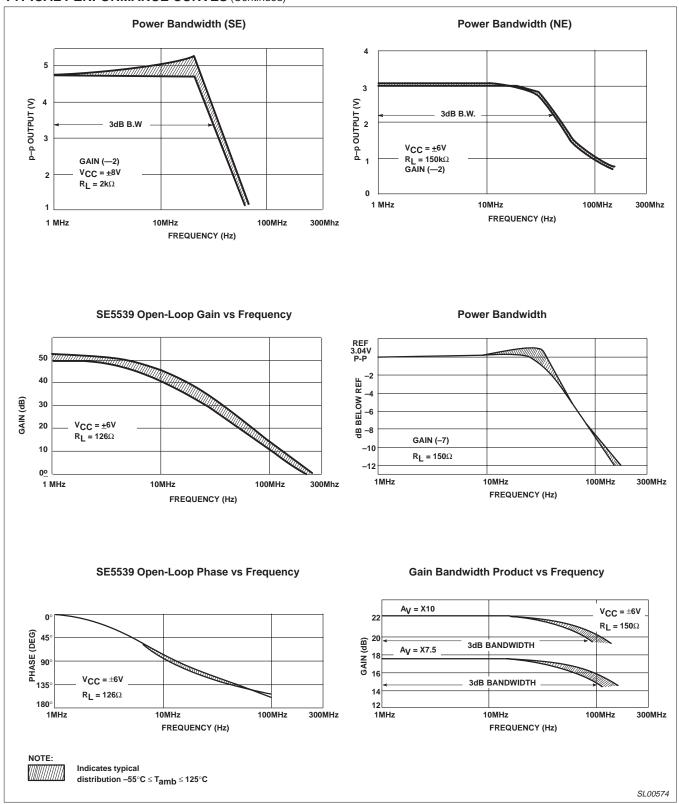


Figure 5. Typical Performance Curves

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#### **CIRCUIT LAYOUT CONSIDERATIONS**

As may be expected for an ultra-high frequency, wide-gain bandwidth amplifier, the physical circuit is extremely critical.

Bread-boarding is not recommended. A double-sided copper-clad printed circuit board will result in more favorable system operation. An example utilizing a 28 dB non-inverting amp is shown in Figure 6.

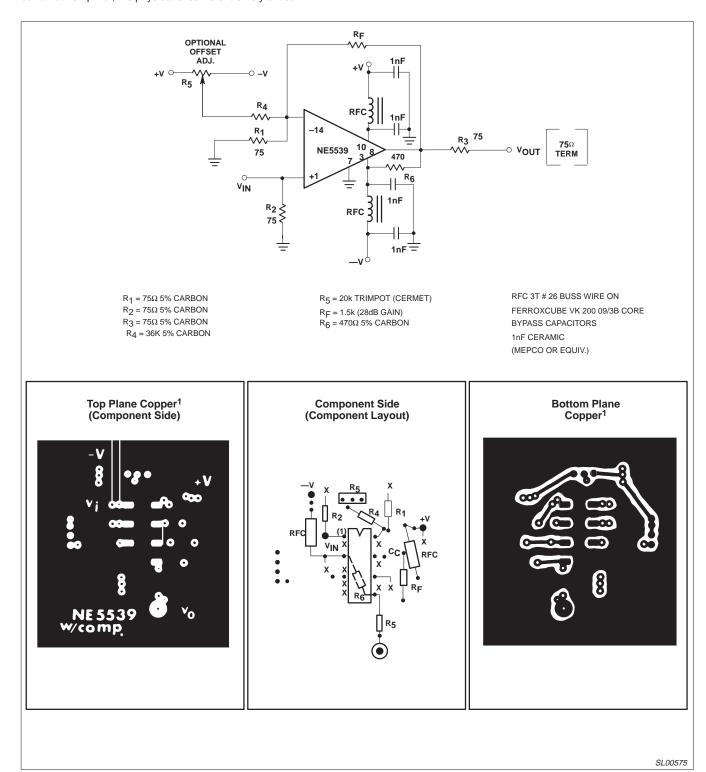


Figure 6. 28dB Non-Inverting Amp Sample PC Layout

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#### **NE5539 COLOR VIDEO AMPLIFIER**

The NE5539 wideband operational amplifier is easily adapted for use as a color video amplifier. A typical circuit is shown in Figure 7 along with vector-scope1 photographs showing the amplifier differential gain and phase response to a standard five-step modulated staircase linearity signal (Figures 8, 9 and 10). As can be seen in Figure 9, the gain varies less than 0.5% from the bottom to the top of the staircase. The maximum differential phase shown in Figure 10 is approximately +0.1°.

The amplifier circuit was optimized for a 75  $\Omega$  input and output termination impedance with a gain of approximately 10 (20 dB).

#### NOTE:

1. The input signal was 200 mV and the output 2 V.  $V_{CC}$  was  $\pm 8$  V.

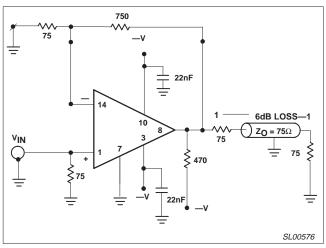


Figure 7. NE5539 Video Amplifier

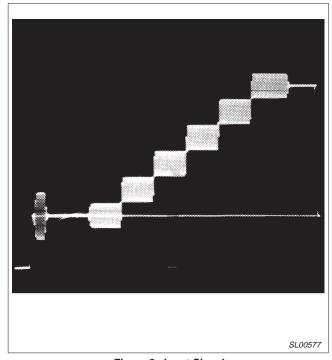


Figure 8. Input Signal

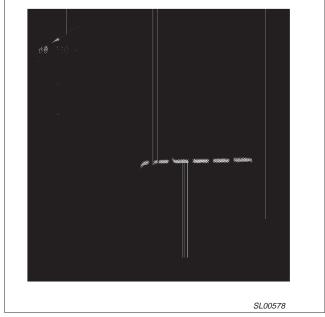


Figure 9. Differential Gain < 0.5%

#### NOTE:

Instruments used for these measurements were Tektronix 146 NTSC test signal generator, 520A NTSC vectorscope, and 1480 waveform monitor.

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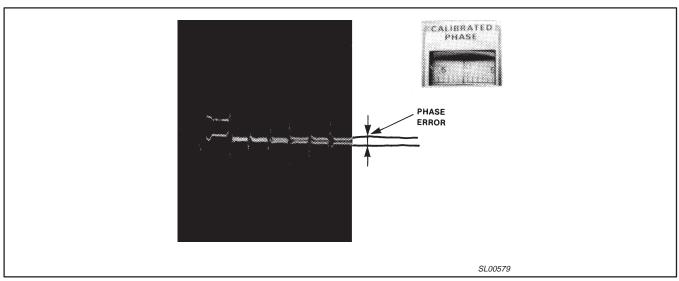


Figure 10. Differential Gain +0.1°

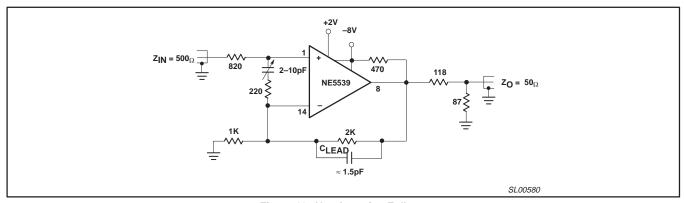


Figure 11. Non-Inverting Follower

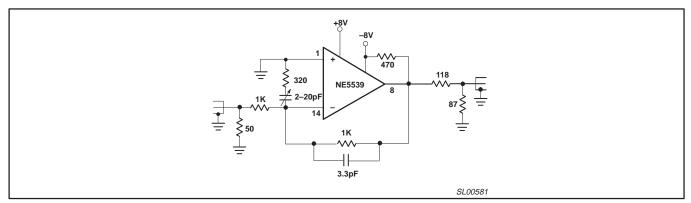


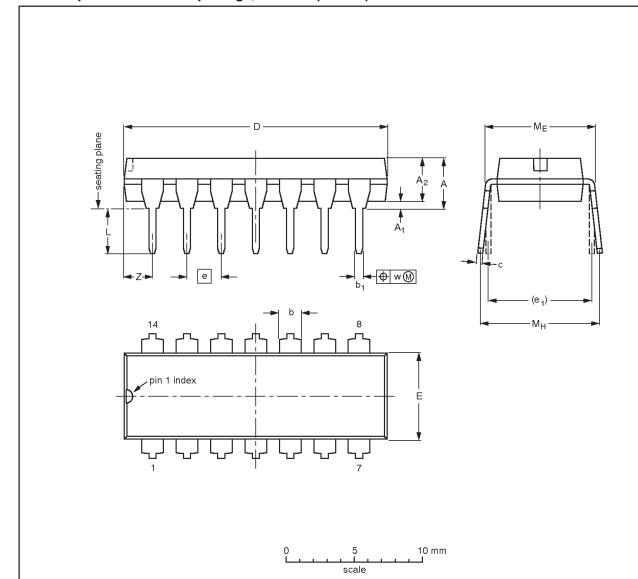
Figure 12. Inverting Follower

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

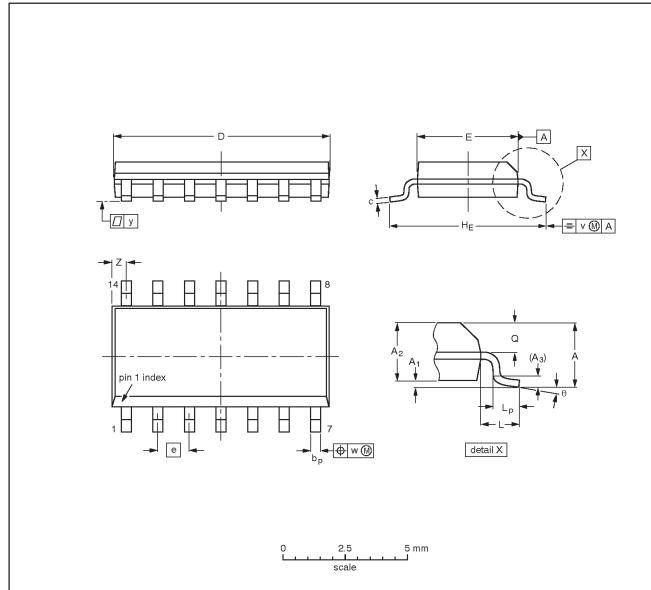
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT27-1	050G04	MO-001	SC-501-14			<del>95-03-11</del> 99-12-27

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#### SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	e	HE	L	Lp	Q	>	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFEF	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT108-1	076E06	MS-012			<del>97-05-22</del> 99-12-27	

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**NOTES** 

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#### Data sheet status

Data sheet status <sup>[1]</sup>	Product status <sup>[2]</sup>	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development.  Philips Semiconductors reserves the right to change the specification in any manner without notice.
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